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SHEET 1 OF 1

<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)</b>				ATTY. DOCKET NO. 005199 USA/Consilium/Consilium		SERIAL NO. 09/725,908  <div style="text-align: center; font-weight: bold; font-size: 1.2em;">RECEIVED</div> <div style="text-align: center;">OCT 10 2003</div>	
				APPLICANT Yueshian T. CHI et al.		Technology Center 2100	
				FILING DATE November 30, 2000		GROUP 2152	

U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
✓	5,901,313	05/04/99	Wolf et al.			09/02/97
✓	6,002,989	12/14/99	Shiba et al.			04/01/97
✓	6,094,688	07/25/00	Mellen-Garnett et al.			03/12/98
✓	6,340,602	01/22/02	Johnson et al.			02/12/01
✓	6,345,288	02/05/02	Reed et al.			05/15/00
✓	6,368,879	04/09/02	Toprac			09/22/99
✓	US-2002/0107604	08/08/02	Riley et al.			12/06/00
✓	6,470,230	10/22/02	Toprac et al.			01/04/00
✓	6,482,660	11/19/02	Conchieri et al.			03/19/01
✓	6,567,717	05/20/03	Krivokapic et al.			01/19/00

FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
✓	WO 99/59200	11/18/99	WIPO			X	
✓	WO 01/52319	07/19/01	WIPO			X	

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)	
✓	Williams, Randy, Dadi Gudmundsson, Kevin Monahan, Raman Nurani, Meryl Stoller and J. George Shanthikumar. October 1999. "Optimized Sample Planning for Wafer Defect Inspection," <i>Semiconductor Manufacturing Conference Proceedings, 1999 IEEE International Symposium on Santa Clara, CA</i> . Piscataway, NJ. pp. 43 - 46.
✓	23 July 2003. Invitation to Pay Additional Fees and Communication Relating to the Results of the Partial International Search for PCT/US02/19116.
✓	01 August 2003. Written Opinion for PCT/US01/27406.
✓	20 August 2003. Written Opinion for PCT/US01/22833.

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~	3,205,485	09/07/65	Noltingk			10/21/60
~	3,229,198	01/11/66	Libby			09/28/62
~	4,000,458	12/28/76	Miller et al.			08/21/75
~	4,302,721	11/24/81	Urbanek et al.			05/15/79
~	4,750,141	06/07/88	Judell et al.			11/26/85
~	4,757,259	07/12/88	Charpentier			11/05/86
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~	5,283,141	02/01/94	Yoon et al.			03/05/92
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~	5,553,195	09/03/96	Meijer			09/29/94
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~	5,642,296	06/24/97	Saxena			07/29/93
~	5,646,870	07/08/97	Krivokapic et al.			02/13/95
~	5,649,169	07/15/97	Berezin et al.			06/20/95
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~	5,666,297	09/09/97	Britt et al.			05/13/94

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✓	5,667,424	09/16/97	Pan			09/25/96
✓	5,674,787	10/07/97	Zhao et al.			01/16/96
✓	5,719,796	02/17/98	Chen			12/04/95
✓	5,735,055	04/07/98	Hochbein et al.			04/23/96
✓	5,761,064	06/02/98	La et al.			10/06/95
✓	5,777,901	07/07/98	Berezin et al.			09/29/95
✓	5,787,021	07/28/98	Samaha			12/18/95
✓	5,787,269	07/28/98	Hyodo			09/19/95
✓	5,825,913	10/20/98	Rostami et al.			07/18/95
✓	5,857,258	01/12/99	Penzes et al.			05/12/94
✓	5,910,846	06/08/99	Sandhu			08/19/97
✓	5,943,237	08/24/99	Van Boxem			10/17/97
✓	5,960,185	09/28/99	Nguyen			06/24/96
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✓	6,036,349	03/14/00	Gombar			07/26/96
✓	6,064,759	05/16/00	Buckley et al.			11/06/97
✓	6,072,313	06/06/00	Li et al.			06/17/97
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✓	6,108,092	08/22/00	Sandhu			06/08/99
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✓	6,136,163	10/24/00	Cheung et al.			03/05/99
✓	6,141,660	10/31/00	Bach et al.			07/16/98
✓	6,143,646	11/07/00	Wetzel			06/03/97
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/	6,159,644	12/12/00	Satoh et al.			03/06/96
/	6,161,054	12/12/00	Rosenthal et al.			09/17/98
/	6,169,931	01/02/01	Runnels			06/29/98
/	6,172,756	01/09/01	Chalmers et al.			12/11/98
/	6,173,240	01/09/01	Sepulveda et al.			11/02/98
/	6,191,864	02/20/01	Sandhu			02/29/00
/	6,204,165	03/20/01	Ghoshal			06/24/99
/	6,210,983	04/03/01	Atchison et al.			06/15/99
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/	6,217,412	04/17/01	Campbell et al.			08/11/99
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—	6,324,481	11/27/01	Atchison et al.			06/15/99
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—	6,336,841	01/08/02	Chang			03/29/01
—	2002/0032499	03/14/02	Wilson et al.			05/04/01
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—	6,368,883	04/09/02	Bode et al.			08/10/99
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—	6,388,253	05/14/02	Su			11/02/00
—	2002/0058460	05/16/02	Lee et al.			09/14/01
—	6,395,152	05/28/02	Wang			07/02/99
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—	6,405,096	06/11/02	Toprac et al.			08/10/99
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—	2002/0070126	06/13/02	Sato et al.			09/19/01
—	2002/0081951	06/27/02	Boyd et al.			02/20/02
—	2002/0089676	07/11/02	Pecen et al.			04/26/00
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—	2002/0127950	09/12/02	Hirose et al.			03/08/01
—	6,455,937	09/24/02	Cunningham			03/17/99

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/	2002/0149359	10/17/02	Crouzen et al.			08/18/01
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/	6,479,990	11/12/02	Mednikov et al.			06/18/01
/	2002/0185658	12/12/02	Inoue et al.			06/14/01
/	2002/0193902	12/19/02	Shanmugasundram et al.			06/18/02
/	2002/0197745	12/26/02	Shanmugasundram et al.			08/31/01
/	2002/0197934	12/26/02	Paik			11/30/01
/	2002/0199082	12/26/02	Shanmugasundram et al.			06/18/02
/	6,503,839	01/07/03	Gonzales et al.			07/03/01
/	2003/0020909	01/30/03	Adams et al.			04/09/01
/	2003/0020928	01/30/03	Ritzdorf et al.			07/09/01
/	6,517,413	02/11/03	Hu et al.			10/25/00

FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
/	61-66104	04/04/86	Japan			X	
/	3-202710	09/04/91	Japan			X	
/	8-23166	01/23/96	Japan			X	
/	9-246547	09/19/97	Japan			X	
/	WO 98/05066	02/05/98	WIPO			X	
/	10-34522	02/10/98	Japan			X	
/	0 869 652	10/07/98	Europe			X	
/	WO 99/09371	02/25/99	WIPO			X	
/	0 910 123	04/21/99	Europe			X	
/	0 932 194	07/28/99	Europe			X	
/	WO 00/00874	01/06/00	WIPO			X	
/	2000-183001	06/30/00	Japan			X	

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						Yes	No
/	1 071 128	01/24/01	Europe			X	
/	WO 01/18623	03/15/01	WIPO			X	
/	WO 01/25865	04/12/01	WIPO			X	
/	434103	05/16/01	Taiwan			X	
/	436383	05/28/01	Taiwan			X	
/	455938	09/21/01	Taiwan			X	
/	455976	09/21/01	Taiwan			X	
/	2001-284299	10/12/01	Japan			X	
/	2001-305108	10/31/01	Japan			X	
/	2002-9030	01/11/02	Japan			X	
/	WO 02/074491	09/26/02	WIPO			X	
/	2002-343754	11/29/02	Japan			X	

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/	Lin, Kuang-Kuo and Costas J. Spanos. November 1990. "Statistical Equipment Modeling for VLSI Manufacturing: An Application for LPCVD." <i>IEEE Transactions on Semiconductor Manufacturing</i> , v. 3, n. 4, pp. 216-229.
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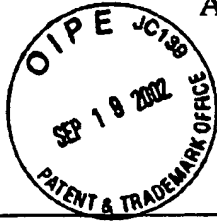
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APPLICANT  
Yueshian T. CHI et al.

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November 30, 2000

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—	6,175,777	01/16/01	Kim			01/16/98
—	6,178,390	01/23/01	Jun			09/08/98
—	6,185,324	02/06/01	Ishihara et al.			01/31/95
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—	6,197,604	03/06/01	Miller et al.			10/01/98
—	6,211,094	04/03/01	Jun et al.			08/23/99
—	6,226,792	05/01/01	Goiffon et al.			10/14/98
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—	6,236,903	05/22/01	Kim et al.			09/25/98
—	6,240,330	05/29/01	Kurtzberg et al.			05/28/97

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						Yes	No
—	11-135601	05/21/99	Japan				X
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—	6,345,315	02/05/02	Mishra			08/12/98
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—	WO 00/79355 A1	12/28/00	WO			X	
—	2001-76982	03/23/01	Japan				X
—	WO 01/33501 A1	05/10/01	WO			X	

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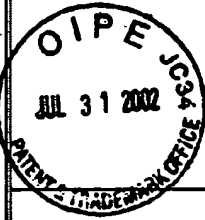
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						Yes	No
—	2,050,247	08/29/91	Canada			X	
—	2,165,847	08/29/91	Canada			X	
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—	05-216896	08/27/93	Japan				X
—	05-266029	10/15/93	Japan				X
—	06-110894	04/22/94	Japan				X
—	06-176994	06/24/94	Japan				X
—	06-252236	09/09/94	Japan				X
—	06-260380	09/16/94	Japan				X
—	1072967A3	11/21/01	Europe			X	

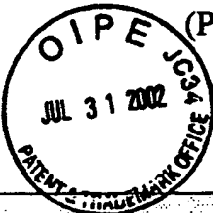

**OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)**

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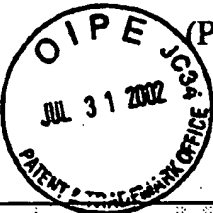

<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION</b>				ATTY. DOCKET NO. 5199/Consilium/MBE		SERIAL NO. 09/725,908	
				APPLICANT Yuehshian T. CHI et al.			
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<b>U.S. PATENT DOCUMENTS</b>							
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<b>FOREIGN PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT/ PUBLICATION NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
<b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b>							
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				<b>APPLICANT</b> Yuehshian T. CHI et al.			
				<b>FILING DATE</b> November 30, 2000		<b>GROUP</b> 2152	
<b>U.S. PATENT DOCUMENTS</b>							
<b>EXAMINER'S INITIALS</b>	<b>PATENT NO.</b>	<b>DATE</b>	<b>NAME</b>	<b>CLASS</b>	<b>SUBCLASS</b>	<b>FILING DATE</b>	
<b>FOREIGN PATENT DOCUMENTS</b>							
<b>EXAMINER'S INITIALS</b>	<b>PATENT/ PUBLICATION NO.</b>	<b>DATE</b>	<b>COUNTRY</b>	<b>CLASS</b>	<b>SUBCLASS</b>	<b>Translation</b>	
						Yes	No
<b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b>							
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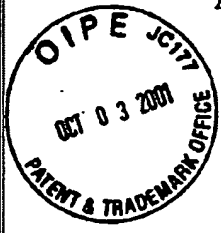
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
—	HEI 1-283934	11/15/89	Japan			X	
—	HEI 8-149583	06/07/96	Japan			X	
—	HEI 9-34535	02/07/97	Japan			X	
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<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION</b>  <div style="display: flex; align-items: center; justify-content: center;">  <div>             (PTO-1449)           </div> </div>				ATTY. DOCKET NO. 5199/Consilium/MBE		SERIAL NO. 09/725,908	
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						Yes	No

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EXAMINER'S INITIALS	PATENT APPLICATION NO.	FILING DATE	NAME	TITLE	CLASS	SUB-CLASS			
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—	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium					
—	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System					
/	09/637,620	08/11/00	Chi et al.	Generic Interface Builder					
/	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers					
<b>FOREIGN PATENT DOCUMENTS</b>									
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUB-CLASS	Translation			
						Yes	No		
<b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b>									
/	Dishon, G., M. Finarov, R. Kipper, J.W. Curry, T. Schraub, D. Trojan, 4 <sup>th</sup> Stambaugh, Y. Li and J. Ben-Jacob. February 1996. "On-Line Integrated Metrology for CMP Processing." Santa Clara, California: VMIC Speciality Conferences, 1 <sup>st</sup> International CMP Planarization Conference.								
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				APPLICANT Yuehshian T. CHI et al.			
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<b>U.S. PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT APPLICATION NO.	FILING DATE	NAME	TITLE	CLASS	SUB- CLASS	
—	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service			
<b>FOREIGN PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUB- CLASS	Translation  Yes No	
<b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b>							
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